

ABSTRACT

A semiconductor chip with test pads and a tape carrier package using the same are provided. The tape carrier package comprises a semiconductor chip. The semiconductor chip has an active surface and a back surface. The active surface has a main circuit area having integrated circuits and a peripheral area having chip pads connected to the integrated circuits. The semiconductor chip has test pads connected to the chip pads for testing the characteristics of the integrated circuits. The tape carrier package further comprises a tape wiring substrate having an insulating base film, wiring patterns formed on the insulating base film, leads formed integrally with the wiring patterns and dummy leads electrically isolated from the wiring patterns, and bumps connecting the chip pads to the corresponding leads and the test pads to the dummy leads.